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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/797,003	03/11/2004	Akiji Shibata	503.43552X00	3868
20457 7590	09/22/2005		EXAM	INER
•	ΓERRY, STOUT & KΙ	CHAMBLISS, ALONZO		
1300 NORTH SE SUITE 1800	VENTEENTH STREET		ART UNIT	PAPER NUMBER
ARLINGTON, V	/A 22209-3873		2814	

DATE MAILED: 09/22/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

		m /		
•	Application No.	 \	Applicant(s)	
	10/797,003		SHIBATA ET AL.	
Office Action Summary	Examiner		Art Unit	
	Alonzo Chambliss		2814	
The MAILING DATE of this communication app Period for Reply	pears on the cover she	et with the c	correspondence addi	ress
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a repl - If NO period for reply is specified above, the maximum statutory period of - Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailine earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, m y within the statutory minimum will apply and will expire SIX (6) e, cause the application to becor	ay a reply be tin of thirty (30) day MONTHS from ne ABANDONE	nely filed s will be considered timely. the mailing date of this com D (35 U.S.C. § 133).	munication.
Status				
1) Responsive to communication(s) filed on 13 M	<u>lay 2004</u> .			
<u> </u>	s action is non-final.			
3) Since this application is in condition for allowa	•			nerits is
closed in accordance with the practice under E	=x parte Quayle, 1935	C.D. 11, 45	53 O.G. 213.	
Disposition of Claims				
4) Claim(s) 1 and 2 is/are pending in the applicat 4a) Of the above claim(s) is/are withdra 5) Claim(s) is/are allowed. 6) Claim(s) 1 and 2 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/o	wn from consideration			
Application Papers				
9)⊠ The specification is objected to by the Examine 10)⊠ The drawing(s) filed on 11 March 2004 is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11)□ The oath or declaration is objected to by the Example 11.	a) accepted or b) accepted or b) additional accepted in about the drawn accepted in the	eyance. See ving(s) is obj	e 37 CFR 1.85(a). jected to. See 37 CFR	
Priority under 35 U.S.C. § 119				
a) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received rity documents have b u (PCT Rule 17.2(a)).	in Applicati een receive	on No ed in this National S	tage
Attachment(s)				
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 3/11/04. 	_ Paper			52)

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DETAILED ACTION

1. The amendment filed on 5/13/04 has been fully considered and made of record in the instant application.

Priority

2. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Information Disclosure Statement

3. The information disclosure statement (IDS) submitted on 3/11/04 was filed before the mailing date of the non-final rejection on 9/19/05. The submission is in compliance with the provisions of 37 CFR 1.97. Accordingly, the information disclosure statement is being considered by the examiner.

Drawings

4. Figures 9-12 should be designated by a legend such as --Prior Art-- because only that which is old is illustrated. See MPEP § 608.02(g). Corrected drawings in compliance with 37 CFR 1.121(d) are required in reply to the Office action to avoid abandonment of the application. The replacement sheet(s) should be labeled "Replacement Sheet" in the page header (as per 37 CFR 1.84(c)) so as not to obstruct any portion of the drawing figures. If the changes are not accepted by the examiner, the

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applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance.

Specification

5. The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed. The following title is suggested: " MOLD DIE FOR A SEMICONDUCTOR DEVICE".

Claim Rejections - 35 USC § 102

6. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States
- 7. Claims 1 and 2 are rejected under 35 U.S.C. 102(b) as being clearly anticipated by Weber (US 6,157,086).

With respect to Claims 1 and 2, Weber teaches a mold die comprising a first die 32 having a recess of a predetermined form and a second flat die 34. The first die to be disposed on a surface of a wiring board 14 (i.e. having a conductive pattern) by the mold compound 16, wherein the wiring board 14 has a plurality of openings 26 and a semiconductor chip 12 mounted on the surface via an elastic material (i.e. solder bumps). The second die 34 is disposed on a back of the surface of the wiring board 14 on which the semiconductor chip 12 is mounted for sealing with an insulating resin 16

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(i.e. by transfer mold process) a periphery of the semiconductor chip 12 and at least one of the opening 26 of the wiring board, wherein the second die 34 comprises a protrusion (i.e. about channel 38) disposed around an area overlapping the opening 26 to be sealed with the insulating resin 16 (see col. 3 lines 20-67, col. 4 lines 1 –67, and col. 6 lines 15-20; Figs. 6-8).

The prior art made of record and not relied upon is cited primarily to show the product of the instant invention.

Conclusion

8. Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonzo Chambliss whose telephone number is (571) 1927.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-7956

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system Status information for published applications may be obtained from either Private PMR or Public PMR. Status information for unpublished applications is available through Private PMR only. For more information about the PMR system see http://pair-dkect.uspto.gov. Should you have questions on access to the Private PMR system contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free) or EBC_Support@uspto.gov.

AC/September 19, 2005

Alonzo Chambliss Primary Patent Examiner

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